

## SimpleLink™ Wi-Fi® CC3000 Module from Texas Instruments

### FEATURES

- **Wireless Network Processor**
  - IEEE 802.11 b/g
  - Embedded IPv4 TCP/IP Stack
- **Best-in-class Radio Performance:**
  - Tx Power: +18dBm at 11Mbps, CCK
  - Rx Sensitivity: –86dBm, 8% PER, 11Mbps
- **Works with low MIPS, Low Cost Microcontrollers with Compact Memory Footprint:**
  - 2KBytes Flash
  - 250Bytes RAM
- **FCC, IC and CE Certified with Chip Antenna**
- **HW Design Files and Design Guide Available from TI**
- **Integrated Crystal and Power Management**
- **Small Form Factor**  
16.3mm x 13.5mm x 2mm
- **Operating Temperature Range:**  
–20°C to 70°C
- **Based in TI's 7th Generation of Proven Wi-Fi Solutions**
- **Complete Platform Solution Including User and Porting Guides, API Guide, Sample Applications, and Support Community**

### APPLICATIONS

- **Home Automation**
- **Home Security**
- **Connected Appliances**
- **Smart Energy**
- **M2M Communication**

### DESCRIPTION

The CC3000 is a self-contained wireless network processor that simplifies the process of implementing Internet connectivity. SimpleLink™ Wi-Fi minimizes host microcontroller (MCU) software requirements making it the ideal solution for embedded applications using any low-cost and low-power MCU.

The CC3000 is provided as a module by TI to reduce development time, lower manufacturing costs, save board space, ease certification and minimize RF expertise required. Additionally, it is provided as a complete platform solution including software drivers, sample applications, API guide, user documentation and a world-class support community.

More information on TI's wireless platform solutions for Wi-Fi can be found on TI's Wireless Connectivity Wiki ([www.ti.com/connectivitywiki](http://www.ti.com/connectivitywiki)).

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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
CC3000MOD	ACTIVE			46	1	TBD	Call TI	Call TI	
CC3000MODR	ACTIVE			46	1200	TBD	Call TI	Call TI	
XCC3000MOD	PREVIEW			46		TBD	Call TI	Call TI	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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